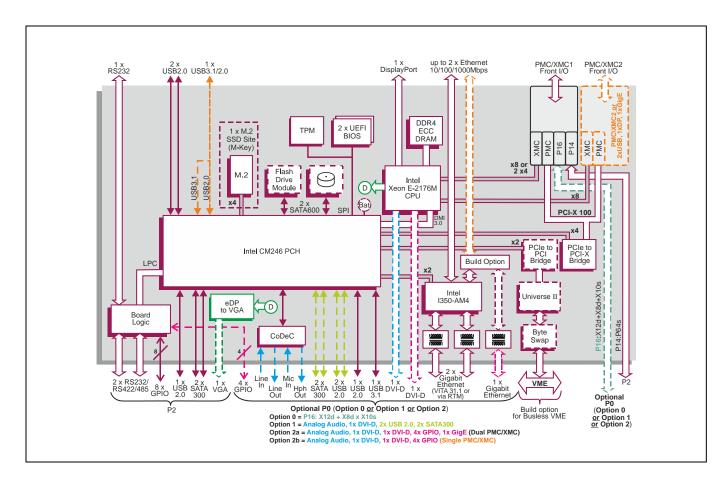
VME board based on Intel® Xeon® processor

Key Features

VP B7x/msd is a high performance, flexible VMEbus board based on a 6-core Intel® Xeon® processor E-2176M (formerly known as Coffee Lake-H). It is designed for long life-cycle applications in the defense, industrial, scientific and aerospace markets.

- Six-core processor and up to 32 Gbytes DDR4 DRAM for high performance applications
- Dual or single PMC/XMC sites for local expansion
- Wide variety of I/O interfaces including SATA, USB, Ethernet, graphics and serial
- Direct attached storage options suitable for operating system, application and data use
- Board support packages for Linux[®], Windows[®] and VxWorks[®]
- Option to exclude VMEbus interface is available







Concurrent Technologies Plc

4 Gilberd Court, Colchester, Essex, CO4 9WN, UK

Tel: +44 (0)1206 752626

Concurrent Technologies Inc.

400 West Cummings Park, Suite 1300, Woburn, MA 01801, USA

Tel: (781) 933 5900

email:info@gocct.com www.gocct.com

Specification

VME Embedded Computer Board

- air-cooled 6U VME computing board utilizing an Intel® Xeon® processor (coded Coffee Lake)
- single or dual XMC sites (build options)
- optional Rear Transition Module (RTM)
- rugged conduction-cooled (RCx-Series) versions:
 - → see VP B7x/msd-RC datasheet

Central Processor

- 6-core Intel® Xeon® processor E-2176M:
 - → 12 Mbytes Smart Cache, 2.7 GHz (45W)
 - → Intel® UHD Graphics 630
- range of performance/power factory build options
- utilizes the Intel® CM246 Platform Controller Hub

- 16 or 32 Gbytes soldered DDR4 ECC DRAM:
 - → single bit error correction
 - dual channel architecture
- accessible from processor or VME bus

PMC/XMC Interfaces

- single or dual PMC/XMC interfaces
- PMC/XMC I/O site 1:
 - → front panel I/O
 - → PMC P14 rear I/O (P64s) via P2
 - → XMC P16 rear I/O (X12d+X8d+X10s) via optional P0 (build option 0)
- PMC/XMC I/O site 2 (or additional front I/O):
 - → front panel I/O: option for PMC/XMC site or extra front panel I/O connectors (USB 3.1/2.0 and Gigabit Ethernet interfaces)
 - → rear I/O: none
- PMC PCI/PCI-X interfaces:
 - → 32/64-bit. 33/66 MHz PCI bus
 - → 64-bit PCI-X bus up to 100 MHz
 - → 5V and 3.3V signaling
- XMC PCI Express interfaces:
 - → both support x8 PCI Express (Gen 1, Gen 2)
 - → XMC site 1 can also support 2 x4 PCI Express
 - → both powered from 5V supply

Ethernet Interfaces

- up to 4 x Gigabit Ethernet interfaces:
 - → implemented by an Intel® I350-AM4 LAN controller via a x2 PCI Express® port (Gen 2)
- 1 x Gigabit Ethernet interface via front panel RJ45
- 2 x Gigabit Ethernet interfaces via optional P0:
 - → via P0 to optional RTM or utilize VITA 31.1 (Gigabit Ethernet for VME64x backplanes)
- 1 x Gigabit Ethernet interface as a build option:
 - → via P0 (build option 2a only)
 - → or via front panel RJ45 (build option 2b only) (disables PMC/XMC site 2):
 - → on-board magnetics (50V isolation via P0)

Serial Interfaces

- 3 x serial channel interfaces:
 - → 1 x RS232 accessed via 60-way high density connector on front panel
 - → 2 x RS232/422/485 accessed via P2
- 16550 compatible UARTs

Mass Storage Interfaces

- up to 4 x external SATA300 interfaces:
 - → 2 x SATA via P2
 - → 2 x SATA (build option 1) via optional P0
- 1 x M.2 SSD site for optional on-board supporting:
- → Type 2242, 2260 or 2280 device
- → x4 PCIe interface (M-key)
- → NVM Express® (NVMe™) logical device interface
- → NVMe 1.3 compatible
- → device can be fitted simultaneously with PMC/XMC modules fitted
- 2242 device can be fitted with 2.5-inch SATA drive fitted
- 2 x SATA600 interfaces for optional on-board:
 - → SATA Flash Drive Module
 - → 2.5-inch SATA drive (disables PMC/XMC Site 2)

Stereo Audio

- Intel® High Definition Audio interface with CoDeC (build options 1 & 2) via optional P0:
 - → line level stereo input and output
 - → line level microphone input
 - → headphone output

Graphics Interfaces

- 1 x DVI-D interface (build option 1) or 2 x DVI-D interfaces (build option 2) via optional P0:
 - → up to 1920 x 1200 @ 16M colors
- 1 x DisplayPort® V1.2 interface via 60-way high density connector on front panel:
 - → up to 1920 x 1200 @ 60Hz
- resolution is dependent on the device driver
- 1 x VGA interface (build option) via P2:
 - → up to 1920 x 1200 @ 16M colors
 - → embedded DisplayPort to VGA converter
- support for Microsoft® DirectX 12, OpenGL 4.5 under Windows® and Linux® and OpenCL 2.1

Other Peripheral Interfaces

- PC Real Time Clock
- watchdog timer; 32-bit Long Duration Timer with processor interrupt ability; chipset timer
- 3 x USB 2.0 ports:
 - → 2 x USB 2.0 via 60-way connector on front panel
 - → 1 x USB 2.0 via P2
- up to 4 x USB ports accessed via optional P0
 - → 1 x USB 2.0 port and 1 x USB 3.1 (Gen 1) port
 - → 2 x USB 2.0 ports (build option 1)
- option for 1 x USB 3.1 (Gen 1) and USB 2.0 ports accessed via USB connector on front panel (disables PMC/XMC site 2)
- 8 x GPIO signals via P2 plus 4 x GPIO signals (build option 2) via optional P0:
 - supports processor interrupt capability
- Write Protect (build option 2) and External Reset (build option 2) via optional P0

Flash EPROM

32 Mbytes of BIOS Flash EPROM, dual devices:

main/backup device enabled via switch

Software Support

support for Linux[®], Windows[®] and VxWorks[®]

Board Security Packages

- Trusted Platform Module (TPM 2.0)
- option for Sanitization Utility Software Package
- option for proprietary board-level security features

Firmware Support

- UEFI 2.7 boot firmware (BIOS):
 - → implements Secure Boot
- implements Intel® Boot Guard
- optional Fast Boot solution using the Intel® Firmware Support Package (FSP)
- LAN boot firmware included

Optional Built-In Test (BIT) Support

Power-on BIT (PBIT), Initiated BIT (IBIT), Continuous BIT (CBIT)

■ PCB (PWB) manufactured with flammability rating of UI 94V-0

VME Interface

- P1 and P2 connectors compatible with VME64x
- implemented using IDT® Universe™ II device
- VME Master/Slave
- A32/A24/A16/D64/D32/D16/D8(EO)/MBLT
- fast hardware byte swapping
- auto system controller detect
- full interrupter / interrupt handler support
- bus error interrupt support
- build option for busless VME interface:
 - → SYSRESET, SYSFAIL, ACFAIL, GAx
 - VMEbus daisy chain

Electrical Specification

- typical current figure for processor (45W) with 16 Gbytes DRAM:
- +5V @ 6.7A
- +12V @ 0.0A; -12V @ 0.0A; 3.3V not required
- +12V and -12V routed to both PMC/XMC sites

Environmental Specification

- operating temperature:
 - → 0°C to +55°C (N-Series)
- extended operating temperatures based upon processor's performance/power factory build

 - → -25°C to +70°C (E-Series)
 - → -40°C to +70°C (K-Series)
- → -40°C to +85°C (K-Series)
- non-operating temperature: -40°C to +85°C
 - 5% to 95% Relative Humidity, non-condensing:

→ K-Series includes humidity sealant Mechanical Specification

- 6U form-factor
- single slot, width 0.8-inch (20.3mm)
- utilizes 160-way connectors for P1 and P2
- optional P0 connector IEEE 1101.10 VME64x handles, alternatively with
- option for VME32 handles
- shock: 20g, 11ms, ½ sine vibration: 5Hz-2000Hz at 2g, 0.38mm peak displacement

Legacy Board Compatibility

 VP B7x/msd rear plug compatibility with the popular VP B1x/msd and VP 92x/x1x families

Note: unless otherwise stated I/O interface references to "build option 2" means both build option 2a and build option 2b are supported. See block diagram for details.